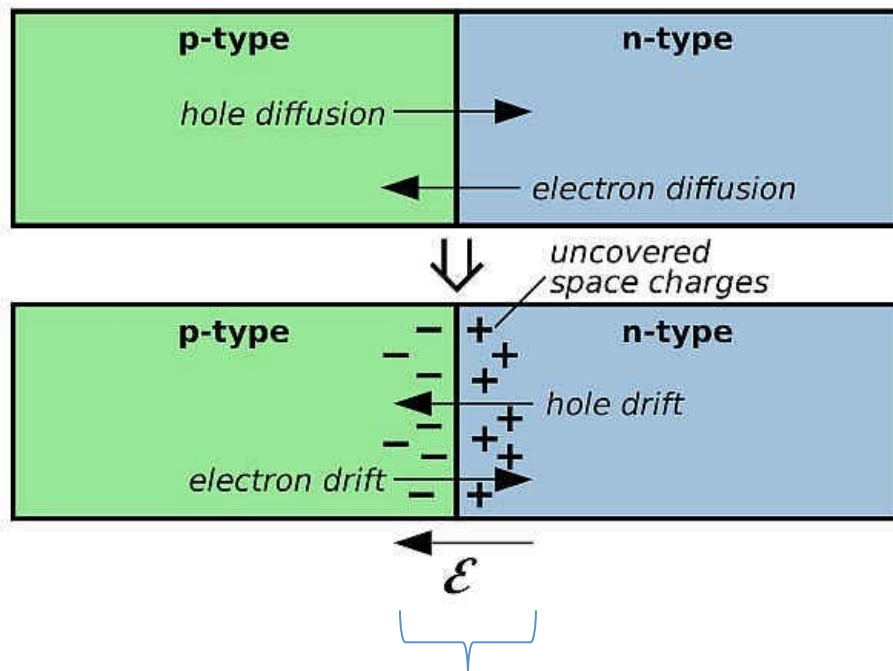


Lab #11 Silicon PV

How PN Junction Works



This image is in the public domain.

Dopant atoms that are left behind are charged, creating a localized electric field

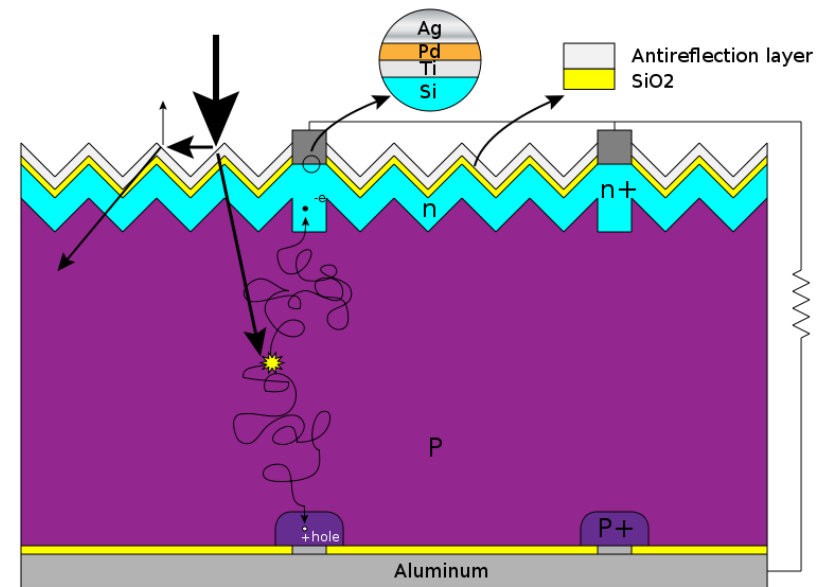


Image courtesy of [Cyferz](#) at [en.wikipedia](#).

Basic structure of a silicon based solar cell and its working mechanism.

Si Solar Cell Fabrication Process

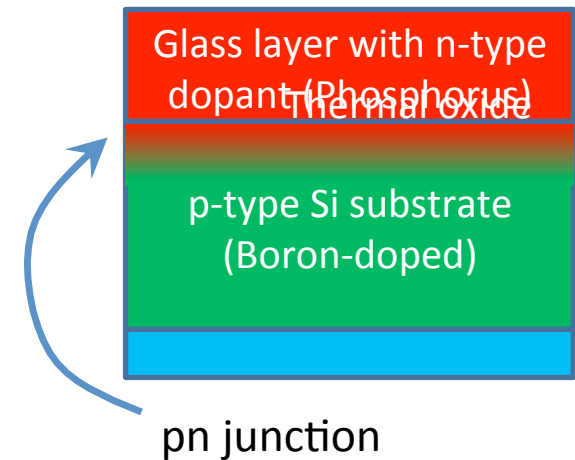
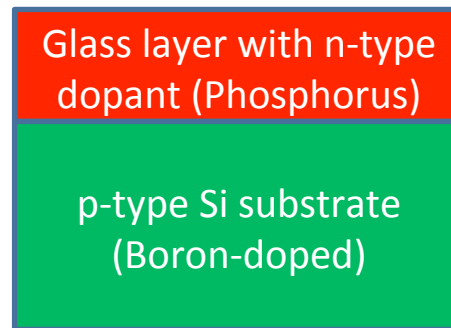
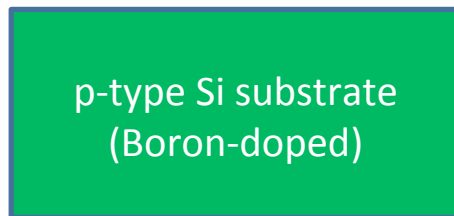
1) Start with p-type Si wafer
(Boron incorporated during growth)



2) Spin-on n-type dopant
(Phosphorus/glass mix)

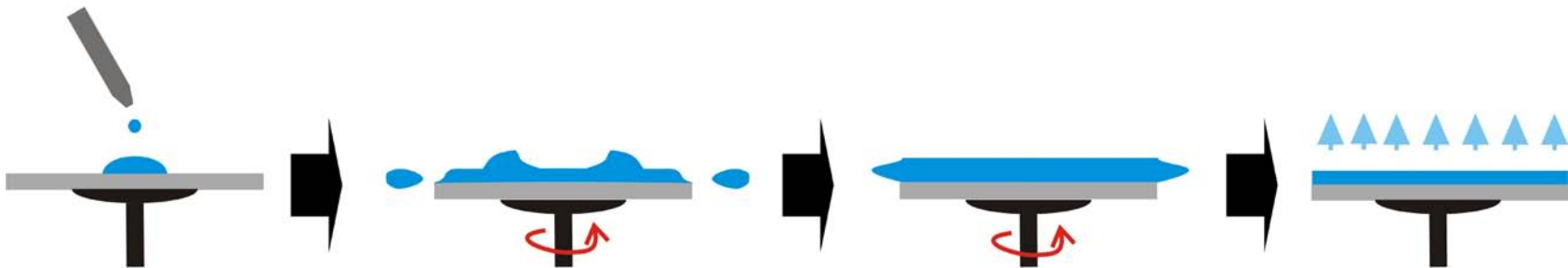


3) Diffuse n-type dopant into
substrate at high temperature
(1000C) for 1.5 hours



Spin Coating

$$h = \frac{h_0}{\left(1 + \frac{4\rho\omega^2 h_0^2 t}{3\eta}\right)^{\frac{1}{2}}}$$



This image is in the public domain.

- Apply uniform thin films to flat substrates by spreading the fluid with centrifugal force
 - The higher the angular speed, the thinner the film
 - The more viscous a solution, the thicker the film

SiO₂ Color Chart

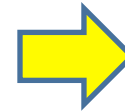
7c:cf`WUfhfYa cj YX`Xi Y`hc`Wdntf][\hfYghf]VW]cbg"
FYZf`hc.`CI]XY`H\JW]bYgg`7c:cf`7\UfhZfca `979`=`]bc]g"

Si Solar Cell Fabrication Process

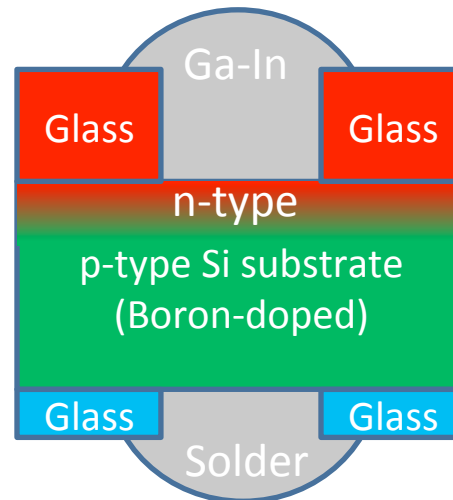
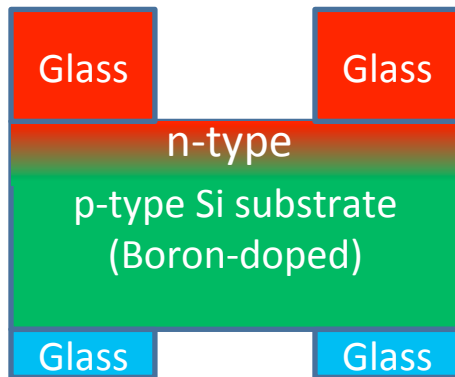
4) Remove glass dopant and thermal oxide layers using glass etchant cream



5) Metallize the front and back



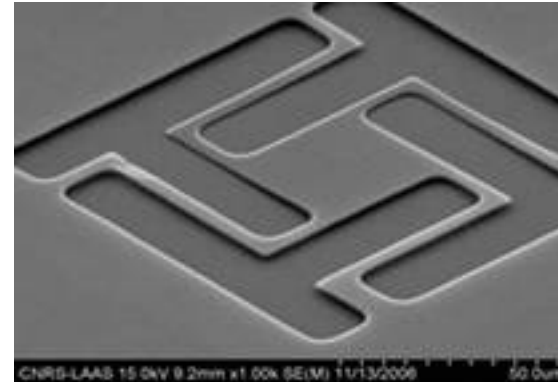
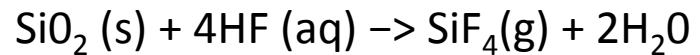
6) Test!!!!



Note: if we're careful about the thickness of our spin-on glass, we can use it as an AR coating

SiO₂ Etching

Frequently aqueous hydrofluoric acid (HF) solutions are used as SiO₂ etchants.



CNRB-LAAB 15.0kV 9.2mm x1.00k (SEI/M) 11/13/2009 50.0um
7ci fhYgmcZ=A H! 6i VWUfYgh'I gYX'k]h`dYfa]gg]cb"

- I. Protons are adsorbed to oxygen on the surface featuring the strongest basicity which functions as the proton acceptor.
- II. Oxygen which adsorbs the proton needs the valence electron.
- III. Oxygen obtains the valence electron from neighboring silicon which has many electrons.
- IV. As silicon gives the valence electron to oxygen, the electron density around silicon gets lower. Consequently the silicon-oxygen bond gets weaker, and the bond is eventually broken.
- V. When the silicon-oxygen bond is broken, silicon becomes positive.
- VI. As a result, HF₂⁻ is coordinated to facilitate etching.

IV Characterization

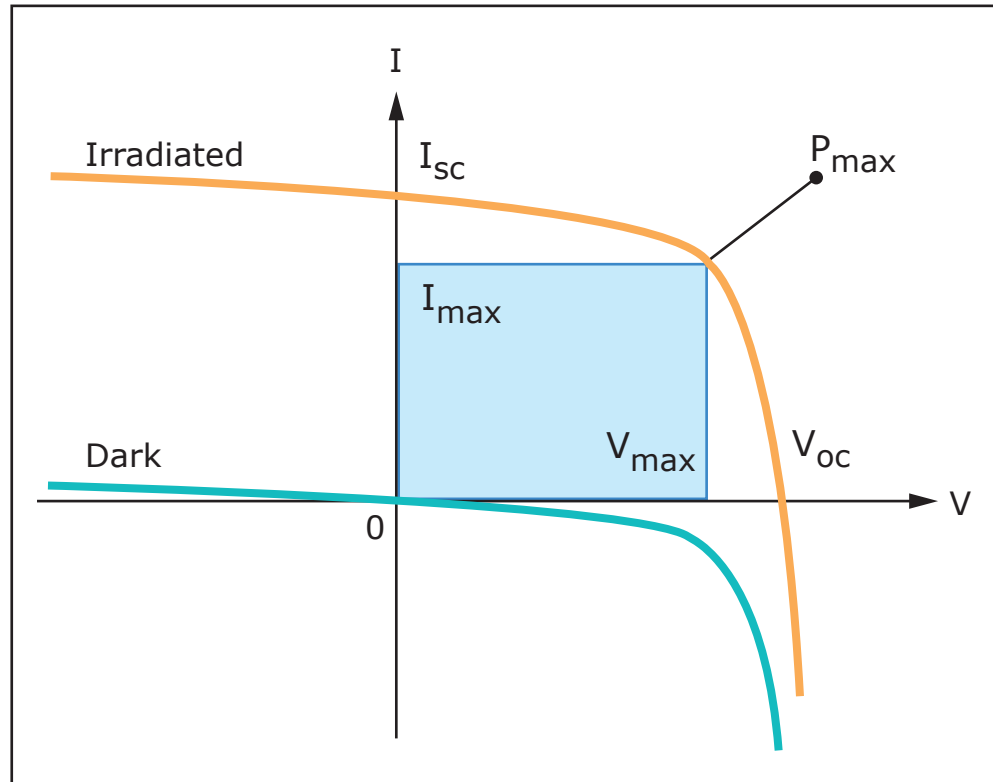


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6.S079 Nanomaker
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